Industrial IO Development Kit Block Diagram

AM1810/AM1808/OMAP-L138
ARM Microprocessor or C6748 DSP Only from Texas Instruments

MityARM/MityDSP
User Programmable Xilinx Spartan 6 FPGA
(available on the MityARM/MityDSP FPGA Modules – Contact Critical Link for additional information)

HID / Thumb drive
PC
SD Card
Disk
Serial
Ethernet
Propsnet
Modbus TCP
EtherCAT Master
CAN
Audio Line Out
RS232
RS485/Profibus
Modbus Monitor
Screen/WQVGA Panel w/Touch or GPIO
Power Management

USB-A Connector
Micro-USB Connector
Micro-SD Connector
SATA Header
10-pin Header
RJ-45 & Magnetics
Expansion Header 3
Expansion Header 2
Expansion Header 1
USB1
USB0
MMCSD 0
SATA
UART[2]
TRSA23E
RS232 PHY
TLK100
Ethernet PHY
ISO 1050
UART[1]
MCP2515
DSD1971
McBSP[1]
10-pin Header
1/8" stereo jack
10-pin Header
I2C[0]
+3.3V
+5V
+12V
-12V
I2C[1]
+3.3V
+5V
+12V
-12V
IO
IO
IO
IO
IO
McBSP[1]
ISO 1 (CAN)
ISO 2 (RS-485)
+(3.3V)
+(3V)
+12V
-12V
5V ISO 1 (CAN)
5V ISO 2 (RS-485)
5V (Audio)
Place filter next to pins 20&21 of DAC.
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